Poster Presentation

[FMCp3]Metrology &Manufacturing

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[FMCp3-5]Post-oven Induced Surface Hydrophobicity Degradation of CF₄ Plasma Treated Polyimide Photo Resistance

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Keywords:polyimide film, hydrophobicity, plasma treatment, bank, post-oven

Polyimide films were treated by CF_4 plasma to serve as bank material for inkjet printing OLED. Excellent hydrophobicity was thus obtained due to the F implantation. However, degradation of hydrophobicity was observed by post-oven, an inevitable process for inkjet printing. This degradation is probably caused by the H_2O/O_2 chemical adsorption.